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(54) **CERAMIC SINTERED COMPACT  
SUBSTRATE, LIGHT-EMITTING DEVICE,  
AND METHODS FOR MANUFACTURING  
CERAMIC SINTERED COMPACT  
SUBSTRATE AND LIGHT-EMITTING  
DEVICE**

(71) Applicant: **NICHIA CORPORATION**, Anan-shi  
(JP)

(72) Inventors: **Akiko NAGAE**, Komatsushima-shi  
(JP); **Masaaki KATSUMATA**,  
Anan-shi (JP)

(73) Assignee: **NICHIA CORPORATION**, Anan-shi  
(JP)

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**ABSTRACT**

A manufacturing method for a ceramic sintered compact substrate including preparing a ceramic substrate, bonding dry films to a first surface and a second surface of the ceramic substrate, performing exposure and development, performing etching or blasting through the dry films formed into a predetermined pattern, forming a first recessed portion recessed relative to a first flat surface portion of the first surface and a second recessed portion recessed relative to a second flat surface portion of the second surface, peeling off the dry films, disposing a metal paste, and firing the metal paste to obtain a metal member. In the method, before the first recessed portion and the second recessed portion are formed, a through hole penetrating through the ceramic substrate is formed, and the metal paste is disposed in the first recessed portion, the second recessed portion, and the through hole.

